

EDCON-COMPONENTS

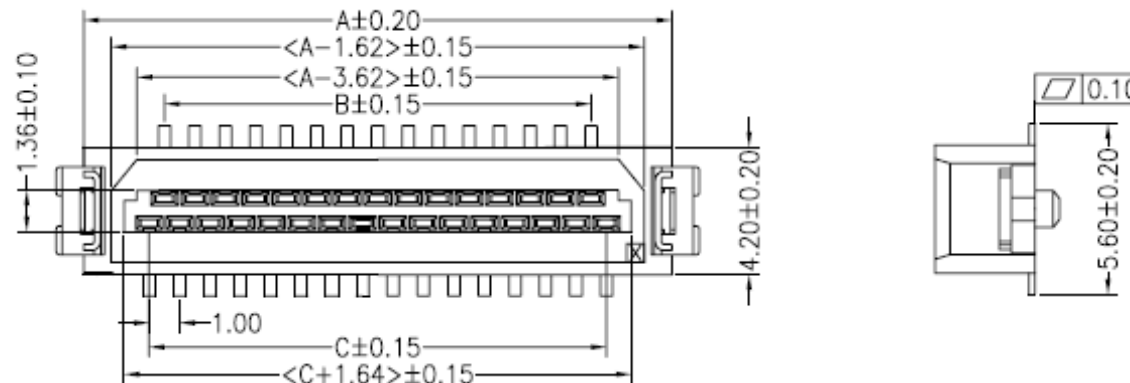


Specifications

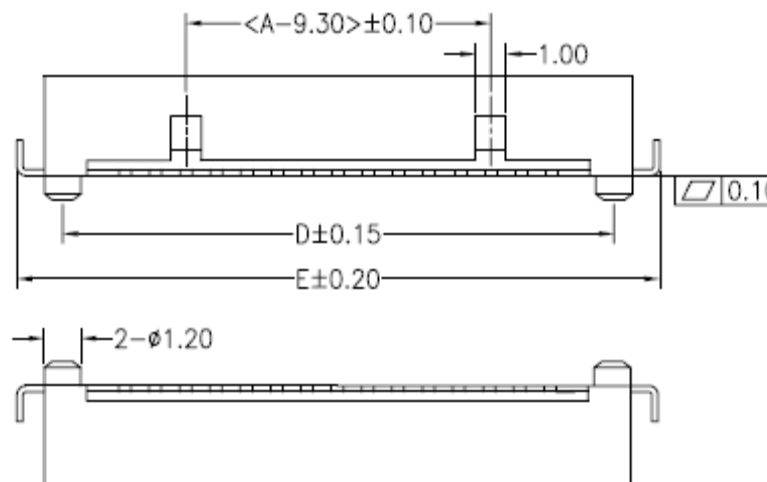
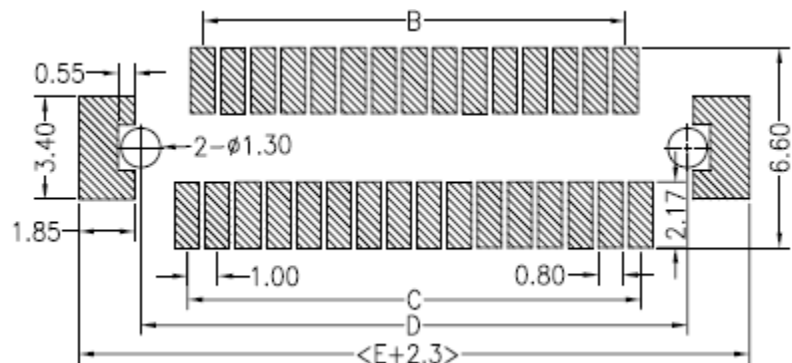
Voltage Rating: 150VAC /DC
 Current Rating 0,5AC / DC
 Operating Temperature . -40°C ~ +105°C
 Contact Resistance 20m Ω Max.
 Withstanding Voltage 250V AC/minute
 Insulation Resistance 100M Ω Min.

Material Insulator: PA46 (UL94V-0)
 Material Pin Brass
 Pin Plating: AU or SN over NI
 9 pin to 15pin without D

Drawing (dimensions all into mm)



PCB Layout



**Wire to Board Serie Pitch
1,00mm**

Part No.: **T68L013**

DRW:	Jason	CHKD	Wilson	MATL:	Wilson	TOLERANCE	Mason	DATE	02.04.2009
APPD:	Schumi			FINISH	Jamy		Sheet No.	1 from 4	Customer:

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Dimension Informations about Wafer

Table 1	Dimension (mm)					
Pos.	A	B	C	D	E	F
9	8,30	3,00	4,00	7,10	10,1	
11	9,30	4,00	5,00	8,10	11,1	
13	10,30	5,00	6,00	9,10	12,1	
15	11,30	6,00	7,00	10,10	13,1	
17	12,30	7,00	8,00	11,10	14,1	
19	13,30	8,00	9,00	12,10	15,1	
21	14,30	9,00	10,00	13,10	16,1	
23	15,30	10,00	11,00	14,10	17,1	
25	16,30	11,00	12,00	15,10	18,1	
31	19,30	14,00	15,00	18,10	21,1	
41	24,30	19,00	20,00	23,10	26,1	
51	29,30	24,00	25,00	28,10	31,1	

Table 1	Dimension (mm)					
Pos.	A	B	C	D	E	F

Wire to Board Serie Pitch 1,00mm	
Part No.:	T68L013
Customer:	

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APPD:	Schumi			FINISH	Jamy		Sheet No.		2 from 4

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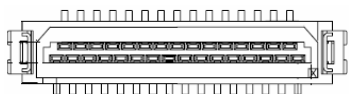
Ordering Informations

Serie	Positions	Body Color	C- Plating	ROHS	Packing				
T68L013	09	BG	TN	R	TU				

Look Table 1	BG= Beige	TN= Tin Plated	R= ROHS Conform	TU= Bulk (Standard)
	WH= White	GF= Gold Flash	N= NON ROHS Conform	TR= Tape Reel
		GA= 3 μ Gold		
		GB= 5 μ Gold		
		GC= 10 μ Gold		
		GD= 15 μ Gold		
		GE= 30 μ Gold		
		SA= Sel. 3 μ Gold		
		SB= Sel. 5 μ Gold		
		SC= Sel. 10 μ Gold		
	SD= Sel. 15 μ Gold	SE= Sel. 30 μ Gold		

Wire to Board Serie Pitch 1,00mm	
Part No.:	T68L013
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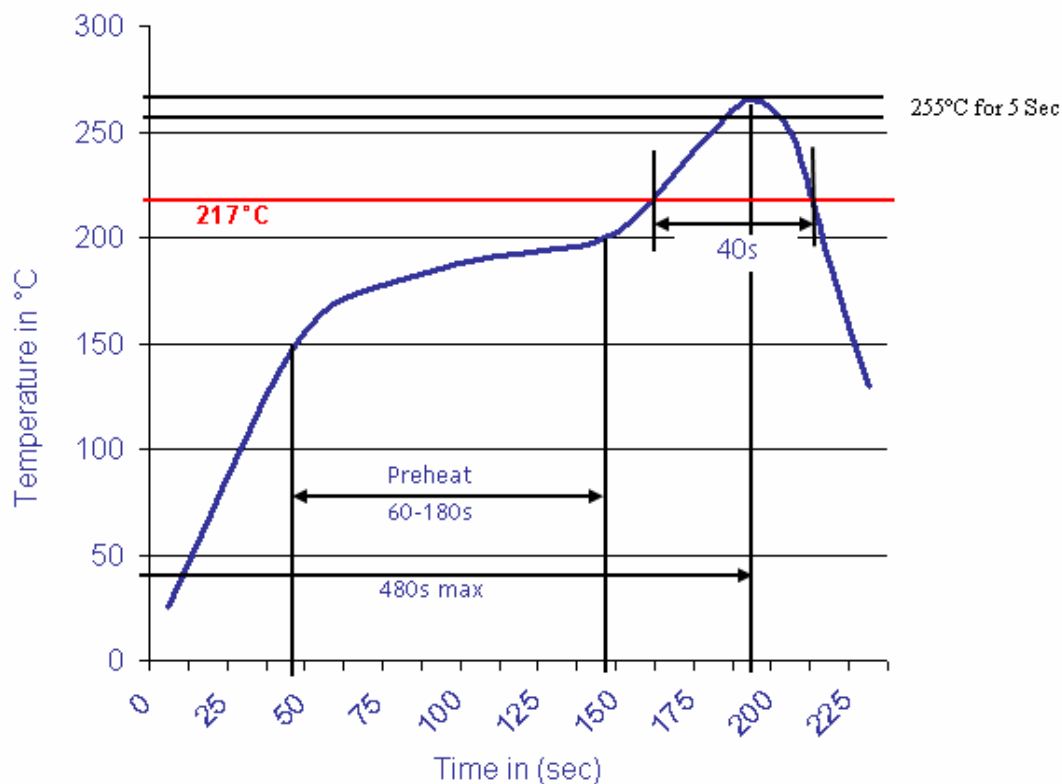
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Soldering Profile

Lead Free Curve

Classification Reflow Profile (JEDEC J-STD-020C)



Wire to Board Serie Pitch 1,00mm	
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